

# MECHANICAL CASE OUTLINE

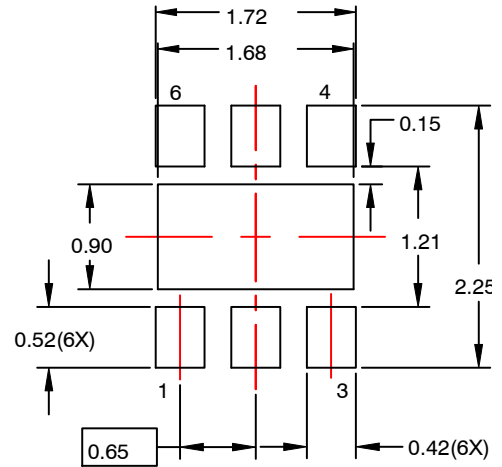
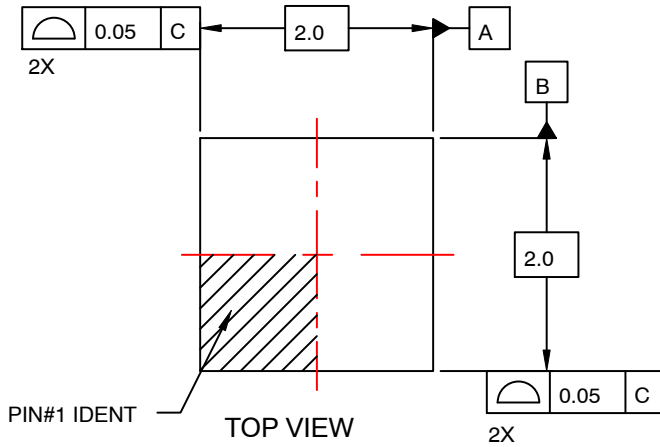
## PACKAGE DIMENSIONS

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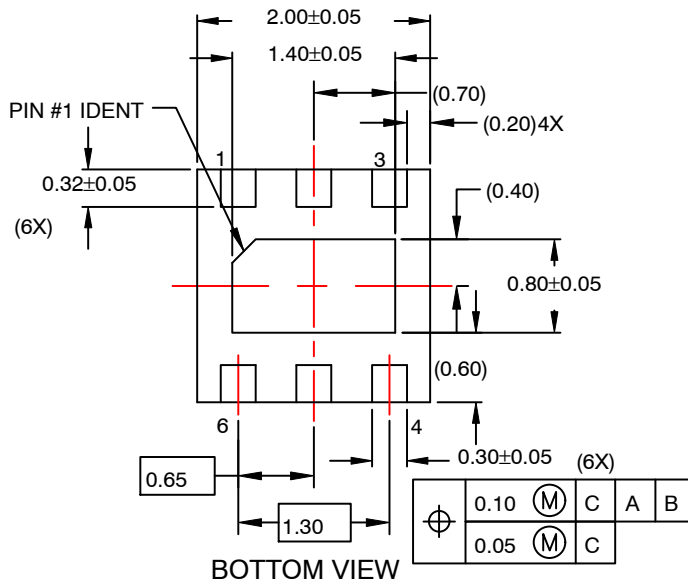
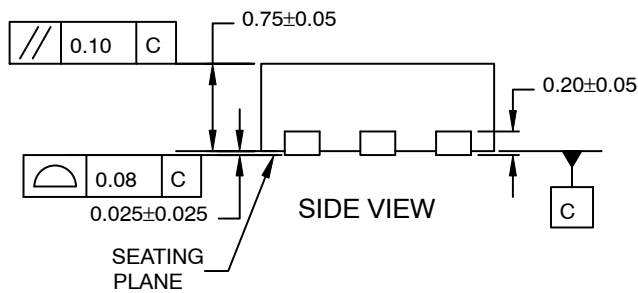


WDFN6 2x2, 0.65P  
CASE 511CY  
ISSUE O

DATE 31 JUL 2016



### RECOMMENDED LAND PATTERN



### NOTES:

- A. PACKAGE DOES NOT FULLY CONFORM TO JEDEC MO-229 REGISTRATION
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

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